

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1 **Claim 1 (original):** An electronic part mounting
2 apparatus for mounting an electronic part on a substrate,
3 comprising:
4 a chamber for cleaning a substrate and an electronic
5 part by plasma;
6 a conveying mechanism for conveying said electronic
7 part and said substrate from said chamber into atmospheric
8 air;
9 a mounting mechanism for receiving said electronic
10 part and said substrate from said conveying mechanism and
11 for mounting said electronic part on said substrate in a
12 state that said electronic part and said substrate are
13 exposed in the atmospheric air.

1 **Claim 2 (original):** An electronic part mounting
2 apparatus according to claim 1,
3 wherein said mounting mechanism includes a part holder
4 for holding said electronic part, a substrate holder for
5 holding said substrate, and a moving mechanism for moving
6 said part holder relative to said substrate holder, and

7 one of said part holder and said substrate holder
8 includes a heating portion for heating objects to be held
9 after said electronic part is mounted on said substrate.

1 **Claim 3 (original):** An electronic part mounting
2 apparatus according to claim 2, wherein heating operation
3 of said heating portion is stopped in the middle of
4 temperature increasing of said objects to be held.

1 **Claim 4 (original):** An electronic part mounting
2 apparatus according to claim 2, wherein both said part
3 holder and said substrate holder include said heating
4 portions.

1 **Claim 5 (currently amended):** An electronic part
2 mounting apparatus according to ~~any of claims~~ claim 1,
3 further comprising an ultrasonic vibration source for
4 applying an ultrasonic vibration to said part holder.

Claims 6-10 (cancelled)

1 **Claim 11 (new):** An electronic part mounting apparatus
2 according to claim 1, further comprising a stage for
3 placing said electronic part and said substrate thereon in
4 said chamber.

1 **Claim 12 (new):** An electronic part mounting apparatus
2 according to claim 1, wherein said substrate and said
3 electronic part are cleaned in one chamber.